

PA-261827

Product Advisory

Issue Date: April 12, 2023

Change Type:

Supply continuity. BOM component change only.

Description and Extent of Change:

The heatsink on Whitney+ 10GBASE-T OCP3.0 adapters is being updated. The updates include changing the finish to black anodized, replacing the nylon pins with brass pins, simplifying the fin construction and removing the heat pipe. Thermal testing of the original and new heatsink shows no measurable difference in thermal performance.

Reasons for Change:

The change is being implement to further enhance supply continuity and standardize heatsink design across the Whitney+ 10GBASE-T OCP3.0 product line.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The adapter specification will remain the same. No changes to adapter form, fit, function, quality and reliability.

Parts Affected:

Part Number	New Revision Number
BCM957416N4160C	18
BCM957416N4160CI	5
BCM957416N4160DC	16
BCM957416N4160HC	20

Effective Date of Change:

The heatsink update is being implemented as a running change. Product shipments start after May 15, 2023.

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.